

Title (en)

ELECTRONIC MICROCOMPONENT, SENSOR AND ACTUATOR INCORPORATING SAME

Title (de)

ELEKTRONISCHES MIKROBAUTEIL SOWIE DIESES ENTHALTENDER SENSOR BZW. ANTRIEB

Title (fr)

MICROCOMPOSANT ELECTRONIQUE, CAPTEUR ET ACTIONNEUR INCORPORANT UN TEL MICROCOMPOSANT

Publication

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Application

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Priority

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Abstract (en)

[origin: WO0201706A1] The invention concerns an electronic microcomponent, produced from a semiconductor substrate wafer (1), comprising two parts, namely a fixed part (10) and a mobile part (11) capable of mutual relative displacement. The invention is characterised in that each part comprises a plurality of plates (20, 21) perpendicular to the main surface of the wafer, the plates (20) of the mobile part (10) being interposed between the plates (21) of the fixed part (11); the plates (21) of the fixed part have an equipotential zone limited by a boundary substantially parallel to the main surface of the wafer (1); the plates (20) of the mobile part (10) have an equipotential zone which, in neutral position, partly covers and extends beyond the surface opposite the equipotential zone of the fixed part (11), such that a difference of potential applied between the equipotential zones of the plates (20, 21) of the fixed (11) and mobile (10') parts, brings about variation in the surface opposite the equipotential zones, and the displacement of the plates (21) of the mobile part perpendicularly to the main surface of the wafer.

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IPC 8 full level

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